

400Gb/S QSFP-DD SR8 Transceiver

P/N: TQSFPDD-JJ1Q85C



Product Features

- Compliant with IEEE 802.3cd Rev. 3.2 200G BASE-SR4
- Compliant to QSFP-DD MSA Rev 2.7 and 3.3
- Supports 400 Gbps data rate links
- Up to 70m/100 m via OM3/OM4, respectively
- Typical power consumption 10W (each port)
- Using standard 2 Row by 12 Channel MPO Connector
- 0°C to 70°C case temperature operating range
- Hot pluggable electrical interface
- RoHS-6 Compliant

Application

- Ethernet for 200GBASE-SR4
- For 400 Gb/s Ethernet Application
- HPC Interconnects
- Proprietary Interconnections

Absolute Maximum Rating

| Parameter | Min | Max | Unit | Note |
|------------------------------------|------|-----|----------------------|------|
| Storage Temperature | -40 | 85 | °C | |
| 3.3V Power Supply Voltage | -0.5 | 3.6 | V | |
| Data Input Voltage- Single Ended | -0.5 | | V _{cc} +0.5 | |
| Control Input Voltage | -0.5 | 3.6 | V | |
| Relative Humidity | 5 | 85 | % | |
| Rx Optical Damage Threshold / Lane | 5 | | dBm | |

Recommended Operating Conditions

| Parameter | Min | Typical | Max | Unit | Note |
|---|----------------------|---------|----------------------|------|------|
| Case Operating Temperature | 0 | | 70 | °C | |
| Power Supply Voltage | 3.135 | 3.3 | 3.465 | V | |
| Data Rate per Channel | | | 26.5625 | Gbps | |
| Control Input Voltage High | 2 | | V _{cc} +0.3 | V | |
| Control Input Voltage Low | -0.3 | | 0.8 | V | |
| Differential Data Input / Output Load | | 100 | | Ohms | ±10% |
| Two Wire Serial (TWS) Interface Clock Rate | | | 1 | MHz | |
| Bit Error Ratio(BER) | 2.4x10 ⁻⁴ | | | | 1,2 |
| Fiber Length: 2000 MHz.km 50/125µm MMF (OM3) | | | 70 | m | |
| Fiber Length: 4700 MHz.km 50/125µm MMF (OM4) | | | 100 | m | |

Note :

1. Bit-Error-Rate (BER) is tested with PRBS 31Q pattern.
2. 400G QSFP-DD SR8 requires an electrical connector compliant with QSFP-DD MSA which is used on the host board in order to guarantee its electrical interface specification.

Electrical Characteristics

| Parameter | Min | Typical | Max | Unit | Note |
|--|-----------|---------|------|------|------|
| Transceiver Electrical Characteristics | | | | | |
| TRx Power Consumption | | 10 | 12 | W | |
| TRx Power-on Initialization Time | | | 2000 | ms | |
| 400CAUI-8 Module Electrical Input Characteristics (TP1) | | | | | |
| Single Ended Input Voltage Tolerance | -0.4 | | 3.3 | V | |
| Differential pk-pk input voltage | | | 880 | mV | |
| Differential Input Return Loss | See Eq. 1 | | | dB | 1 |
| Common to differential mode conversion return loss | See Eq. 2 | | | dB | 2 |
| DC common mode voltage | -0.3 | | 2.8 | V | |

Notes:

$$1. \quad RLd(f) \geq \begin{cases} 9.5 - 0.37f & 0.01 \leq f < 8 \\ 4.75 - 7.4 \log_{10} \left(\frac{f}{14} \right) & 8 \leq f < 19 \end{cases} \quad (\text{dB}) \quad (\text{Eq.1})$$

Where

f is the frequency in GHz

RLd is the CAUI-4 Chip-to-module input differential return loss

$$2. \quad RLdc(f) \geq \begin{cases} 22 - 20 \left(\frac{f}{25.78} \right) & 0.01 \leq f < 12.89 \\ 15 - 6 \left(\frac{f}{25.78} \right) & 12.89 \leq f < 19 \end{cases} \quad (\text{dB}) \quad (\text{Eq.2})$$

where

f is the frequency in GHz

RLdc is the CAUI-4 Chip-to-module input differential to common mode input return loss

| Parameter | Min | Typical | Max | Unit | Note |
|--|-----------|----------|------|------|------|
| CAUI-4 Module Electrical Output Characteristics (TP4) | | | | | |
| Signaling Rate per Lane | | 25.78125 | | Gbps | |
| AC Common-Mode Output Voltage (RMS) | | | 17.5 | mV | |
| Differential Output Voltage | | | 900 | mV | |
| Near-end ESMW (Eye symmetry mask width) | 0.265 | | | UI | |
| Far-end ESMW (Eye symmetry mask width) | 0.2 | | | UI | |
| Near-end Eye Height | 70 | | | mV | |
| Far-end Eye Height | 30 | | 5.5 | mV | |
| Differential Output Return Loss | See Eq. 1 | | | | 1 |
| Common to Differential Mode Conversion Return Loss | See Eq. 2 | | | | 2 |
| Transition Time (20% to 80%) | 9.5 | | | ps | |
| DC Common Voltage | -350 | | 2850 | mV | |

Notes:

$$1. \quad RLd(f) \geq \begin{cases} 9.5 - 0.37f & 0.01 \leq f < 8 \\ 4.75 - 7.4 \log_{10} \left(\frac{f}{14} \right) & 8 \leq f < 19 \end{cases} \quad (\text{dB}) \quad (\text{Eq.1})$$

where

f is the frequency in GHz

RLd is the CAUI-4 Chip-to-module host output differential return loss

$$2. \quad RLdc(f) \geq \begin{cases} 22 - 20 \left(\frac{f}{25.78} \right) & 0.01 \leq f < 12.89 \\ 15 - 6 \left(\frac{f}{25.78} \right) & 12.89 \leq f < 19 \end{cases} \quad (\text{dB}) \quad (\text{Eq.2})$$

where

f is the frequency in GHz

RLdc is the CAUI-4 Chip-to-module output common to differential mode conversion return loss

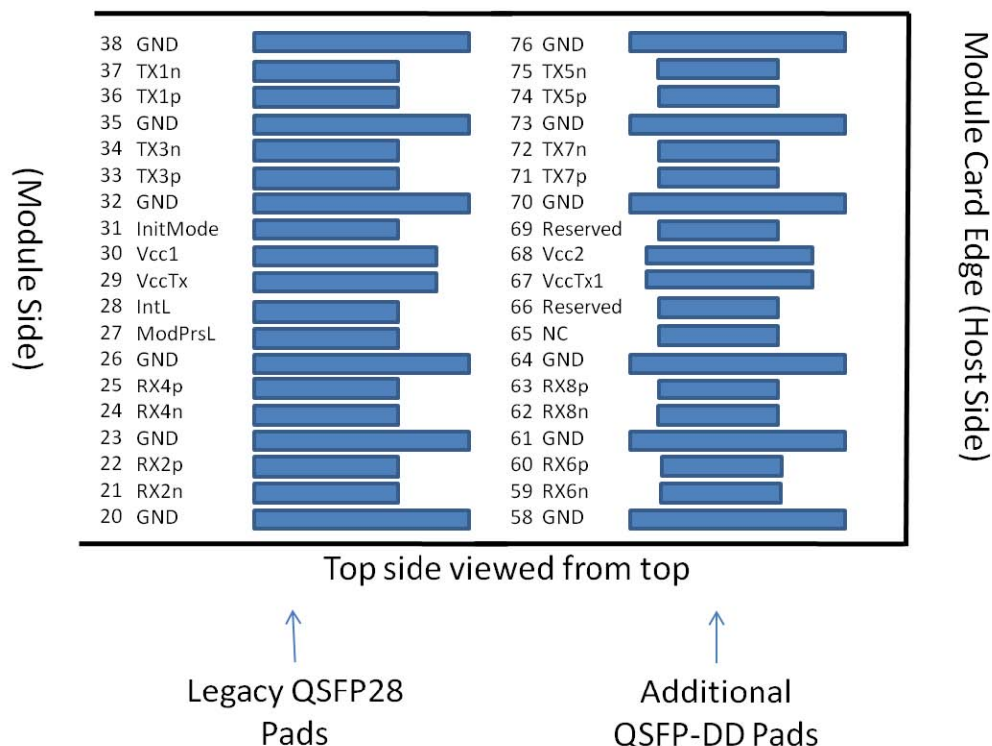
Optical Characteristics

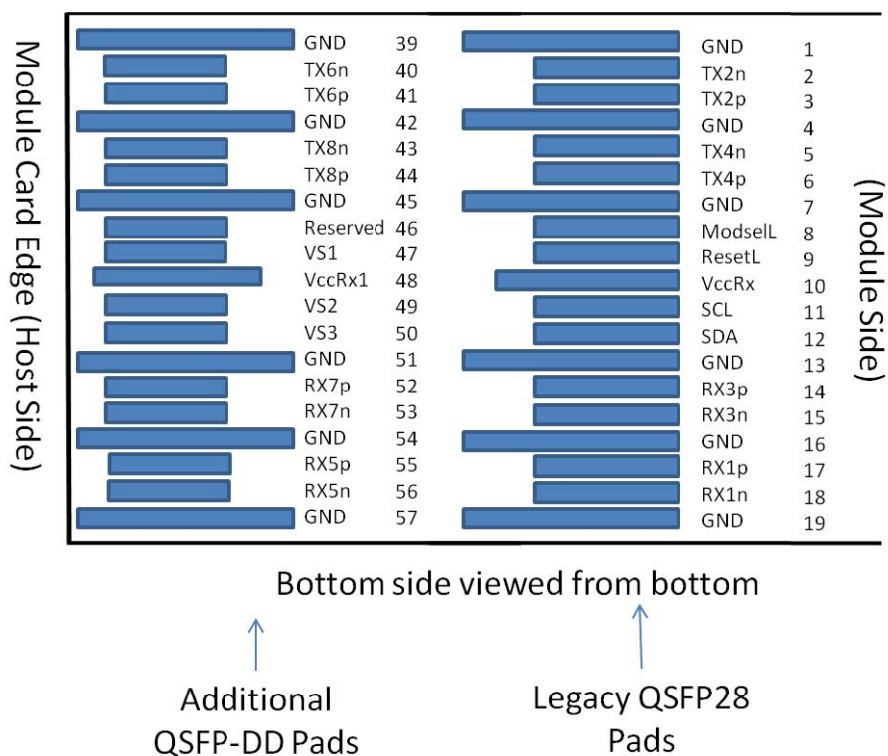
| Parameter | Symbol | Min | Typical | Max | Unit | Note |
|--|-----------------|--|---------|-----|------|------|
| Transmitter Optical Characteristics | | | | | | |
| Center Wavelength | λ | 840 | | 860 | nm | |
| Spectral Width – RMS | $\Delta\lambda$ | | | 0.6 | nm | |
| Average Launch Optical Power, each lane | LOP | -6 | | 4 | dBm | |
| Optical Modulation Amplitude, each lane | OMA | -4 | | 3 | dBm | |
| Launch power in OMA minus TDEC | | -5.9 | | | dBm | |
| Transmitter and dispersion eye closure (TDEC), each lane | TDECQ | | | 4.9 | dB | |
| Average launch power of OFF transmitter, each lane | | | | -30 | dBm | |
| Extinction Ratio | ER | 3 | | | dB | |
| Optical return loss tolerance | | | | 12 | dB | |
| Encircled Flux | | $\geq 86\% @ 19\mu\text{m},$ $\leq 30\% \text{ at } 4.5\mu\text{m}$ | | | | |
| Receiver Optical Characteristics | | | | | | |
| Center wavelength, each lane | λ | 840 | | 860 | nm | |
| Damage Threshold | | 5 | | | dBm | |
| Average power at receiver input, each lane | | -7.9 | | 4 | dBm | 1 |
| Receiver Power, each lane (OMA) | | | | 3 | dBm | |
| Receiver Reflectance | | | | -12 | dB | |
| Stressed sensitivity($\text{OMA}_{\text{outer}}$) | | See Eq.3 | | | dBm | 2,3 |
| Stressed receiver sensitivity in OMA | | | | -3 | dBm | 4 |
| Conditions of stressed receiver sensitivity test: | | | | | | |
| Stressed eye closure (SECQ), lane under test | | | 4.9 | | dB | |
| OMA of each aggressor lane | | | 3 | | dBm | |

Notes:

1. Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.
2. Receiver sensitivity is informative and is defined for a transmitter with a value of SECQ up to 4.9 dB
3. Equation 3: $RS = \text{Max} (-6, \text{SECQ} - 7.9) (\text{dBm})$, where RS is the receiver sensitivity SECQ is the SECQ of the transmitter used to measure the receiver sensitivity
4. Measured with conformance test signal at TP3 for the BER of 2.4×10^{-4}

QSFP-DD Module Pad Assignments and Descriptions





| Pin | Logic | Symbol | Description | Plug Sequence | Notes |
|-----|-------------|---------|-------------------------------------|---------------|-------|
| 1 | | GND | Ground | 1B | 1 |
| 2 | CML-I | Tx2n | Transmitter Inverted Data Input | 3B | |
| 3 | CML-I | Tx2p | Transmitter Non-Inverted Data Input | 3B | |
| 4 | | GND | Ground | 1B | 1 |
| 5 | CML-I | Tx4n | Transmitter Inverted Data Input | 3B | |
| 6 | CML-I | Tx4p | Transmitter Non-Inverted Data Input | 3B | |
| 7 | | GND | Ground | 1B | 1 |
| 8 | LVTTL-I | ModSelL | Module Select | 3B | |
| 9 | LVTTL-I | ResetL | Module Reset | 3B | |
| 10 | | VccRx | +3.3V Power Supply Receiver | 2B | 2 |
| 11 | LVC MOS-I/O | SCL | 2-wire serial interface clock | 3B | |
| 12 | LVC MOS-I/O | SDA | 2-wire serial interface data | 3B | |
| 13 | | GND | Ground | 1B | 1 |
| 14 | CML-O | Rx3p | Receiver Non-Inverted Data Output | 3B | |
| 15 | CML-O | Rx3n | Receiver Inverted Data Output | 3B | 1 |

| | | | | | |
|----|---------|----------|---|----|---|
| 16 | | GND | Ground | 1B | |
| 17 | CML-O | Rx1p | Receiver Non-Inverted Data Output | 3B | |
| 18 | CML-O | Rx1n | Receiver Inverted Data Output | 3B | |
| 19 | | GND | Ground | 1B | 1 |
| 20 | | GND | Ground | 1B | 1 |
| 21 | CML-O | Rx2n | Receiver Inverted Data Output | 3B | |
| 22 | CML-O | Rx2p | Receiver Non-Inverted Data Output | 3B | |
| 23 | | GND | Ground | 1B | 1 |
| 24 | CML-O | Rx4n | Receiver Inverted Data Output | 3B | |
| 25 | CML-O | Rx4p | Receiver Non-Inverted Data Output | 3B | |
| 26 | | GND | Ground | 1B | 1 |
| 27 | LVTTL-O | ModPrsL | Module Present | 3B | |
| 28 | LVTTL-O | IntL | Interrupt | 3B | |
| 29 | | VccTx | +3.3V Power supply transmitter | 2B | 2 |
| 30 | | Vcc1 | +3.3V Power supply | 2B | 2 |
| 31 | LVTTL-I | InitMode | Initialization mode; In legacy QSFP applications, the InitMode pad is called LPMODE | 3B | |
| 32 | | GND | Ground | 1B | 1 |
| 33 | CML-I | Tx3p | Transmitter Non-Inverted Data Input | 3B | |
| 34 | CML-I | Tx3n | Transmitter Inverted Data Input | 3B | |
| 35 | | GND | Ground | 1B | 1 |
| 36 | CML-I | Tx1p | Transmitter Non-Inverted Data Input | 3B | |
| 37 | CML-I | Tx1n | Transmitter Inverted Data Input | 3B | |
| 38 | | GND | Ground | 1B | 1 |
| 39 | | GND | Ground | 1A | 1 |
| 40 | CML-I | Tx6n | Transmitter Inverted Data Input | 3A | |
| 41 | CML-I | Tx6p | Transmitter Non-Inverted Data Input | 3A | |
| 42 | | GND | Ground | 1A | 1 |
| 43 | CML-I | Tx8n | Transmitter Inverted Data Input | 3A | |
| 44 | CML-I | Tx8p | Transmitter Non-Inverted Data Input | 3A | |
| 45 | | GND | Ground | 1A | 1 |
| 46 | | Reserved | For future use | 3A | 3 |

| | | | | | |
|----|-------|----------|-------------------------------------|----|---|
| 47 | | VS1 | Module Vendor Specific 1 | 3A | 3 |
| 48 | | VccRx1 | 3.3V Power Supply | 2A | 2 |
| 49 | | VS2 | Module Vendor Specific 2 | 3A | 3 |
| 50 | | VS3 | Module Vendor Specific 3 | 3A | 3 |
| 51 | | GND | Ground | 1A | 1 |
| 52 | CML-O | Rx7p | Receiver Non-Inverted Data Output | 3A | |
| 53 | CML-O | Rx7n | Receiver Inverted Data Output | 3A | |
| 54 | | GND | Ground | 1A | 1 |
| 55 | CML-O | Rx5p | Receiver Non-Inverted Data Output | 3A | |
| 56 | CML-O | Rx5n | Receiver Inverted Data Output | 3A | |
| 57 | | GND | Ground | 1A | 1 |
| 58 | | GND | Ground | 1A | 1 |
| 59 | CML-O | Rx6n | Receiver Inverted Data Output | 3A | |
| 60 | CML-O | Rx6p | Receiver Non-Inverted Data Output | 3A | |
| 61 | | GND | Ground | 1A | 1 |
| 62 | CML-O | Rx8n | Receiver Inverted Data Output | 3A | |
| 63 | CML-O | Rx8p | Receiver Non-Inverted Data Output | 3A | |
| 64 | | GND | Ground | 1A | 1 |
| 65 | | NC | No Connect | 3A | 3 |
| 66 | | Reserved | For future use | 3A | 3 |
| 67 | | VccTx1 | 3.3V Power Supply | 2A | 2 |
| 68 | | Vcc2 | 3.3V Power Supply | 2A | 2 |
| 69 | | Reserved | For Future Use | 3A | 3 |
| 70 | | GND | Ground | 1A | 1 |
| 71 | CML-I | Tx7p | Transmitter Non-Inverted Data Input | 3A | |
| 72 | CML-I | Tx7n | Transmitter Inverted Data Input | 3A | |
| 73 | | GND | Ground | 1A | 1 |
| 74 | CML-I | Tx5p | Transmitter Non-Inverted Data Input | 3A | |
| 75 | CML-I | Tx5n | Transmitter Inverted Data Input | 3A | |
| 76 | | GND | Ground | 1A | 1 |

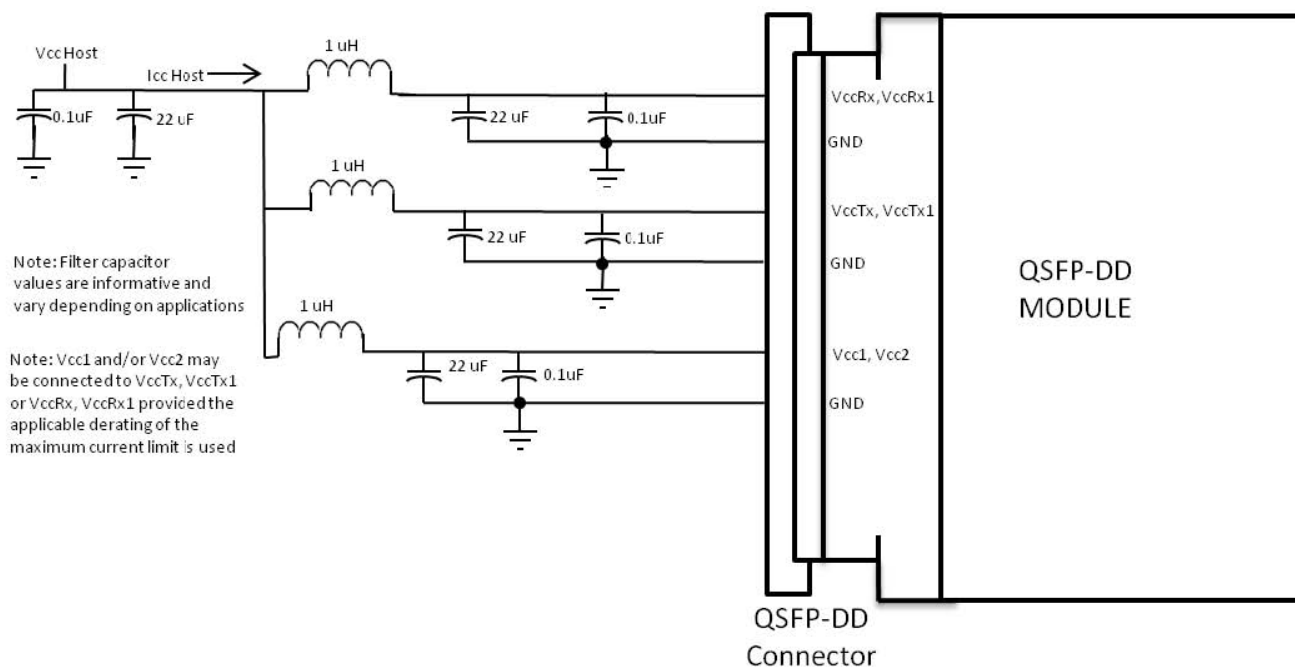
Note:

1. QSFP-DD uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.
2. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently.

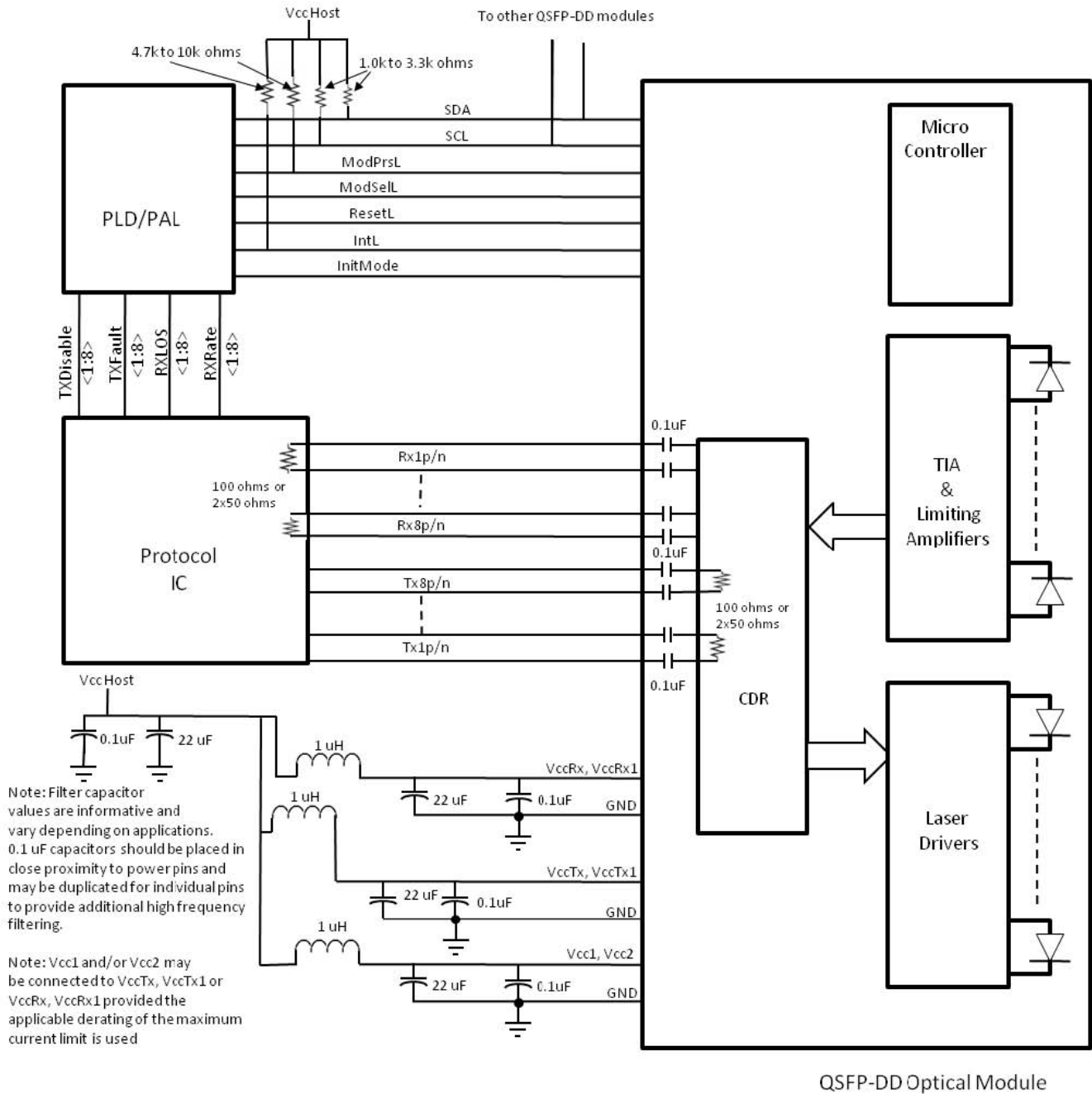
Requirements defined for the host side of the Host Card Edge Connector are listed in Table 6. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.

3. All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 kOhms and less than 100 pF.
4. Plug Sequence specifies the mating sequence of the host connector and module. The sequence is 1A, 2A, 3A, 1B, 2B, 3B. (see Figure 2 for pad locations) Contact sequence A will make, then break contact with additional QSFP-DD pads. Sequence 1A, 1B will then occur simultaneously, followed by 2A, 2B, followed by 3A, 3B

Recommended Host Board Power Supply Circuit

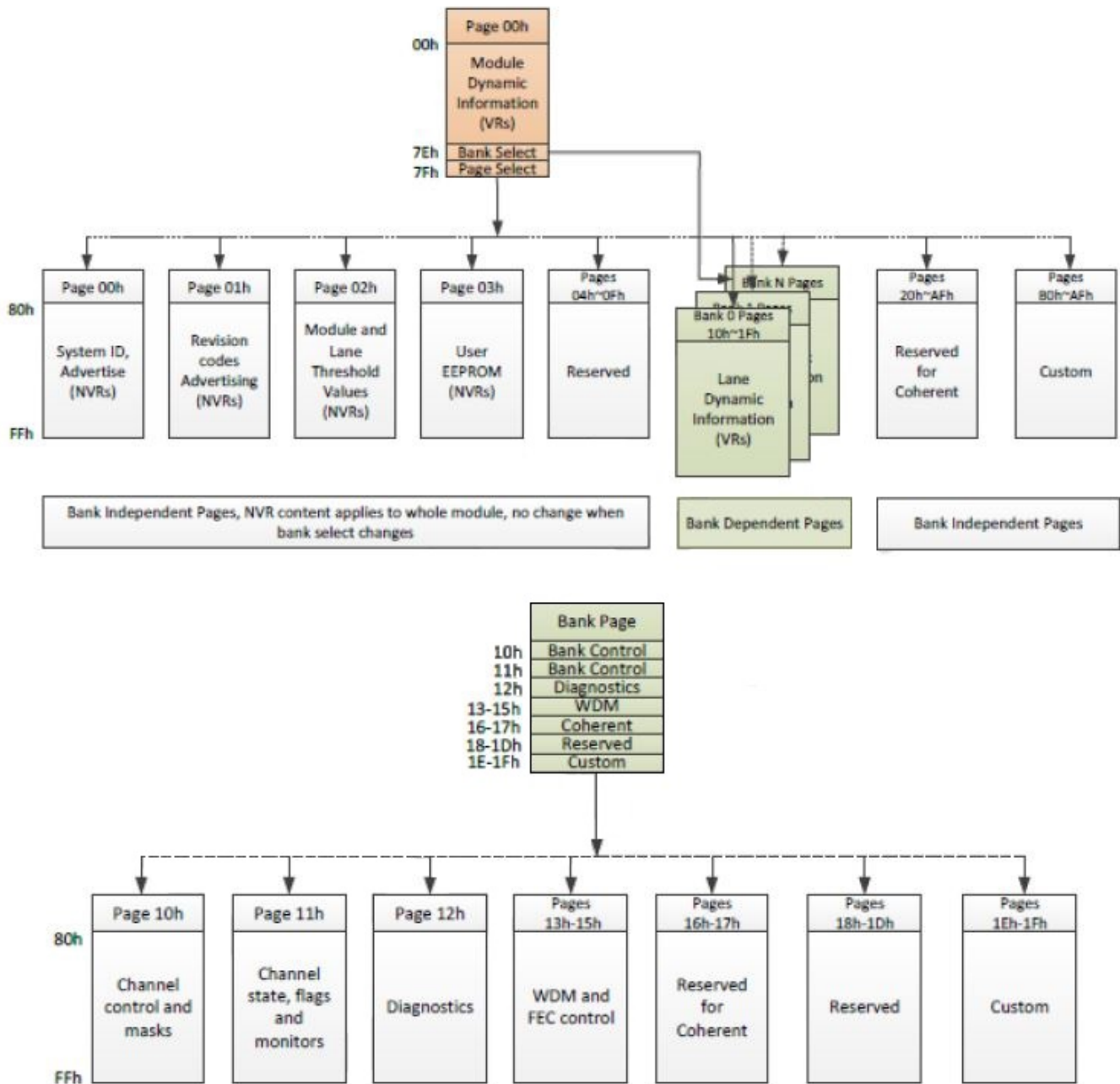


Recommended Interface Circuit



Memory Map

The memory map is structured as a single address and multiple page approaches, according to the QSFP-DD rev.2.7 specification as shown in the below. For more detailed description of this memory map, please see our Memory Map document with flexible customization settings



Technical drawing of a mechanical part, showing three views: front, side, and top. The drawing includes various dimensions and tolerances.

Front View (Top):

- Overall length: 127.20 ± 0.20
- Distance from left end to first hole: 35 max
- Distance between holes: 48.20 min
- Distance from right end to last hole: 3 ± 0.15
- Distance from right end to last hole (bottom): 0.50 ± 0.15
- Overall height: 19 max
- Distance from right end to last hole (bottom): 18.35 ± 0.10
- Distance from right end to last hole (bottom): 2.40 ± 0.05
- Distance from right end to last hole (bottom): 1.70 ± 0.10
- Distance from right end to last hole (bottom): 5.81
- Distance from right end to last hole (bottom): 5.20
- Distance from right end to last hole (bottom): 6 ± 0.10
- Distance from right end to last hole (bottom): 2.40 ± 0.05
- Distance from right end to last hole (bottom): 2 ± 0.15
- Distance from right end to last hole (bottom): 2.50 ± 0.05
- Distance from right end to last hole (bottom): 5.70 ± 0.05
- Distance from right end to last hole (bottom): 2.30
- Distance from right end to last hole (bottom): 29.60 ± 0.10
- Distance from right end to last hole (bottom): 8.50 ± 0.10
- Distance from right end to last hole (bottom): 10.06 ± 0.15
- Distance from right end to last hole (bottom): $16.60 \begin{smallmatrix} +0.10 \\ 0 \end{smallmatrix}$

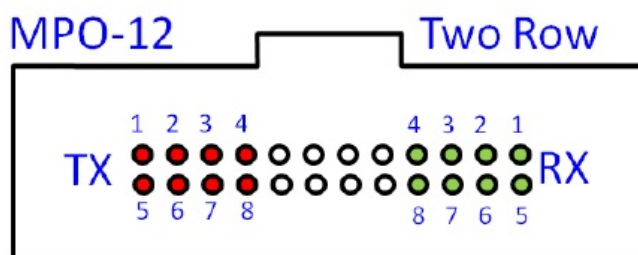
Side View (Middle):

- Overall length: 3.40 max
- Distance from left end to first hole: 1.60 max

Top View (Bottom):

- Overall width: 14.50
- Distance from left end to first hole: 25.60
- Distance from left end to first hole: $2-2$
- Distance from left end to first hole: $2-0.50$
- Distance from left end to first hole: 13.68 ± 0.10
- Distance from left end to first hole: 16.40 ± 0.10

Optical-Channel Definition for 2 Row 12C Fiber



Regulatory Compliance Table

| Item | Compliance | Note |
|--|--|------|
| Electrostatic Discharge (ESD) to the Electrical Contacts | JEDEC Human Body Model (HBM) (JESD22-A114-B) | 1 |
| Electrostatic Discharge (ESD) | EN 61000-4-2 | |
| Electromagnetic Interference (EMI) | 47 CFR FCC Rules and Regulations Part 15 Subpart B, Class B Digital Device EN 55032:2015/AC:2016, Class B | |
| Immunity | EN 55024:2010/A1:2015 | |
| Laser Safety | EN 60825-1:2007 and IEC 60825-1:2014 | |

Note:

1: The 400G QSFP-DD SR8 samples are on-going to be prepared for these testing items